

## **J304**

## **N-Channel RF Amplifier**

- This device is designed for electronic switching applications such as low ON resistance analog switching.
- Sourced from process 50.



#### 1. Drain 2. Source 3. Gate

## **NPN Epitaxial Silicon Transistor**

## **Absolute Maximum Ratings\*** $T_C=25$ °C unless otherwise noted

Symbol	Parameter	Ratings	Units	
$V_{DG}$	Drain-Gate Voltage	30	V	
$V_{GS}$	Gate-Source Voltage	-30	V	
I <sub>GF</sub>	Forward Gate Current	10	mA	
$T_J$ , $T_{STG}$	Operating and Storage Junction Temperature Range	-55 ~ 150	°C	

<sup>\*</sup> This ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

## Electrical Characteristics T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units	
Off Charac	Off Characteristics						
V <sub>(BR)GSS</sub>	Gate-Source Breakdwon Voltage	$I_G = -1.0 \mu A, V_{DS} = 0$	-30			V	
I <sub>GSS</sub>	Gate Reverse Current	$V_{GS} = -20V, V_{DS} = 0$			-100	pА	
V <sub>GS</sub> (off)	Gate-Source Cutoff Voltage	$V_{DS} = 15V, I_D = 1.0nA$	-2.0		-6.0	V	
On Characteristics							
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current	V <sub>DS</sub> = 15V, VGS = 0	5.0		15	mA	
gfs	Forward Transconductance	$V_{GS} = 0V, V_{DS} = 15V, f = 1KHz$	4500		7500	μS	
goss	Output Conductance	$V_{GS} = 0V, V_{DS} = 15V, f = 1KHz$			50	μS	

## Thermal Characteristics $T_A=25$ °C unless otherwise noted

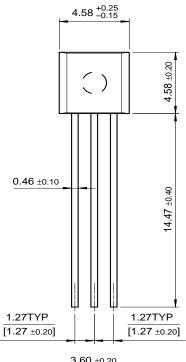
Symbol	Parameter	Max.	Units
P <sub>D</sub>	Total Device Dissipation	350	mW
	Derate above 25°C	2.8	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

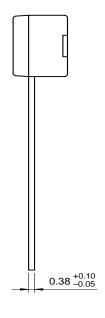
<sup>\*</sup> Device mounted on FR-4 PCB 1.5" × 1.6" × 0.06

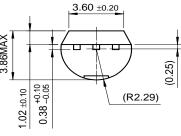
These rating are based on a maximum junction temperature of 150 degrees C.
These are steady limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

# **Package Dimensions**

TO-92







#### **TRADEMARKS**

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

$ACEx^{TM}$	FACT™	ImpliedDisconnect™	PACMAN™	SPM <sup>TM</sup>
ActiveArray™	FACT Quiet series™	ISOPLANAR™	POP™	Stealth™
Bottomless™	FAST <sup>®</sup>	LittleFET™	Power247™	SuperSOT™-3
CoolFET™	FASTr™	MicroFET™	PowerTrench <sup>®</sup>	SuperSOT™-6
CROSSVOLT™	FRFET™	MicroPak™	QFET™	SuperSOT™-8
DOME™	GlobalOptoisolator™	MICROWIRE™	$QS^{TM}$	SyncFET™
EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic™
E <sup>2</sup> CMOS™	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	$I^2C^{TM}$	$OCX^{TM}$	RapidConfigure™	UHC™
Across the board.	. Around the world.™	OCXPro™	RapidConnect™	UltraFET <sup>®</sup>
The Power Franchise™		OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	$VCX^{TM}$
Programmable Ad	ctive Droop™	OPTOPLANAR™	SMART START™	

#### **DISCLAIMER**

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

### **LIFE SUPPORT POLICY**

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the user.
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

### **PRODUCT STATUS DEFINITIONS**

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.